

PACKAGING PROCESS

ABSTRACT OF THE DISCLOSURE

A packaging process of an electronic component is provided. By the packaging process of the disclosure, the electronic component is grinded by the back grinding process. Consequently, thickness of the electronic component may be reduced to less than or equal to $50\ \mu\text{m}$. The packaging process may achieve ultra-thin thickness and reduce the space of the power module. Moreover, the packaging process forms the contact pads with drilling process and grinding process without photolithography process. Consequently, the packaging process is advantageous because of lower cost and uniform thickness of the contact pads.

Fig. 10